



In The United States Patent and Trademark Office

Appn Number: 10/718383  
Appn. Filed: 11-19-03  
Applicant: T. Massingill  
Appn. Title: Semiconductor Package with Recess for Die  
  
Examiner: Alexander O. Williams

Mailed: March 18, 2006  
At: Los Gatos, CA

**Amendment C**

Commissioner for Patents  
PO Box 1450,  
Alexandria, VA 22313-1450

Sir:

In response to the office action mailed Oct. 20, 2005, please amend the application as follows:

**Specification:**

**Page 4 line 19** Modify paragraph 4 as follows.

"It is an object of the invention to provide a cavity down ball grid array package in which the recess has substrate circuitry" -- in the total recess area, and the circuitry allows multiple signal types and voltages under the die.

**Page 5 line 11** Modify the last sentence of paragraph 3 as follows.

"Therefore, the recess has substrate circuitry" --, in the total recess area, -- "for electrical connections to the die, which are made by wirebonds, TAB, or solder balls."